### 504116169 11/30/2016

# PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
SHINICHIRO MATSUO	08/26/2005
TOSHINORI OTAKA	08/26/2005

#### **RECEIVING PARTY DATA**

Name:	MICRON TECHNOLOGY, INC.	
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Postal Code:	83706-9632	

### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Patent Number:	8132138

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ATTORNEY DOCKET NUMBER:	APT2005-0234C01	
NAME OF SUBMITTER:	SHARRON CASTILLO	
SIGNATURE:	/Sharron Castillo/	
DATE SIGNED:	11/30/2016	

#### **Total Attachments: 3**

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PATENT 504116169 REEL: 040466 FRAME: 0678

Docket No.: M4065,1211/P1211

#### ASSIGNMENT AND AGREEMENT

For value received, we, Shinichiro Matsuo and Toshinori Otaka, hereby sell, assign and transfer to Micron Technology, Inc., a corporation of the State of Delaware, having an office at 8000 S. Federal Way, Boise, Idaho 83706-9632, U.S.A., and its successors, assigns and legal representatives, the entire right, title and interest, for the United States of America, in and to certain inventions related to an invention entitled LONG WIRE BUFFERING TECHNIQUE USING STRUCTURED DELAY SKEWING, described in an application for Letters Patent of the United States, executed by us of even date herewith, and all the rights and privileges in said application and under any and all Letters Patent that may be granted in the United States for said inventions; and we also concurrently hereby sell, assign and transfer to Micron Technology, Inc. the entire right, title and interest in and to said inventions for all countries foreign to the United States, including any earlier filed foreign application, all rights of priority arising from the application aforesaid, and all the rights and privileges under any and all forms of protection, including Letters Patent, that may be granted in said countries foreign to the United States for said inventions.

We authorize Micron Technology, Inc. to make application for such protection in its own name and maintain such protection in any and all countries foreign to the United States, and to invoke and claim for any application for patent or other form of protection for said inventions, without further authorization from us, any and all benefits, including the right of priority provided by any and all treaties, conventions, or agreements.

We hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any document which may be required in any country in proof of the right of Micron Technology, Inc. to apply for patent or other form of protection for said inventions and to claim the aforesaid benefit of the right of priority.

We request that any and all patents for said inventions be issued to Micron Technology, Inc. in the United States and in all countries foreign to the United States, or to such nominees as Micron Technology, Inc. may designate.

1

Docket No.: M4065.1211/P1211

We agree that, when requested, we shall, without charge to Micron Technology, Inc. but at its expense, sign all papers, and do all acts which may be necessary, desirable or convenient in connection with said applications, patents, or other forms of protection.

August 26'05

Witness:

Joshik Systi 8/26 '05

Witness:

8/26 105

Docket No.: M4065.1211/P1211

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

### ASSIGNMENT AND AGREEMENT

Signature Page for Second Inventor

August 26'05 Date	Tashin Otaka Toshinori Otaka
Witness:  8/26 105  Date	Lacor Takayonagi
Witness:  8/26 '05  Date	Joshik Synti

3

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**RECORDED: 11/30/2016** 

PATENT REEL: 040466 FRAME: 0681